

Ultra Clean Processing of Semiconductor Surfaces IX

von

P Mertens, M Meuris, M Heyns

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Table of Contents

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Photo

Preface

I. Physical Cleaning Methods

Direct Observation of Single Bubble Cavitation Damage for MHz Cleaning H. Tomita, M. Inukai, K. Umezawa and L.N. Ji	3
High Speed Imaging of 1 MHz Driven Microbubbles in Contact with a Rigid Wall A. Zijlstra, T. Janssens, K. Wostyn, M. Versluis, P.W. Mertens and D. Lohse	7
Characterization of a Cavitation Bubble Structure at 230 kHz: Bubble Population, Sonoluminescence and Cleaning Potential A. Otto, T. Nowak, R. Mettin, F. Holsteys and A. Lippert	11
Impact of Megasonic Activation with Different Chemistries on Silicon Surface in Single Wafer Tool G. Briend, P. Besson, T. Salvetat and S. Petitdidier	15
Impacts of Ionization Potentials and Megasonic Dispersion C. Franklin	19
The Influence of Standing Waves on Cleaning with a Megasonic Nozzle T. Janssens, G. Doumen, S. Halder, K. Wostyn, P.W. Mertens and J. Straka	23
Megasonic Sweeping and Silicon Wafer Cleaning J.M. Goodson and R. Nagarajan	27
Removal of Nano-Particles by Aerosol Spray: Effect of Droplet Size and Velocity on Cleaning Performance K. Xu, S. Pichler, K. Wostyn, G. Cado, C. Springer, G.W. Gale, M. Dalmer, P.W. Mertens, T. Bearda, E. Gaulhofer and D. Podlesnik	31
High Aspect Ratio Contact Clean Study in 58nm Flash Device P.C. Yu, C.K. Chen, J.L. Lin, C.N. Wu and H. Matsuo	35
High Velocity Aerosol Cleaning with Organic Solvents: Particle Removal and Substrate Damage M.T. Andreas, K. Wostyn, M. Wada, T. Janssens, K. Kenis, T. Bearda and P.W. Mertens	39
Cleaning Technique Using High-Speed Steam-Water Mixed Spray M. Watanabe, T. Sanada, A. Hayashida and Y. Isago	43
Pattern Collapse and Particle Removal Forces of Interest to Semiconductor Fabrication Process T.G. Kim, K. Wostyn, J.G. Park, P.W. Mertens and A.A. Busnaina	47
Applications of Electrostatic Spray Techniques to Surface Cleaning K. Finster, R. Small, A. Belz, J. Mahoney, J. Perel and J. Gong	51
Analyzing the Collapse Force of Narrow Lines Measured by Lateral Force AFM Using an Analytical Mechanical Model K. Wostyn, T.G. Kim, P.W. Mertens and J.G. Park	55

II. Particle Interactions

Reduced Particle Removal Efficiency Upon Wafer Storage D.M. Knotter, R. Roucou and R. Peyrin	61
Local Distribution of Particles Deposited on Patterned Surfaces F. Wali, D.M. Knotter, T. Bearda and P.W. Mertens	65
Particle Retention Mechanism of Filter in High Temperature Chemical T. Nagafuchi, K. Chiba, I. Funahashi, M. Inukai, H. Yamada, K. Umezawa and H. Tomita	69

Improving Process Control for Copper Electroplating through Filter Membrane Optimization	73
A.W. Wu, G. Cornner and V. Prabhaker	
Particle – Wafer Interactions in Semiaqueous Silicon Cleaning Systems	77
L. Hupka, J. Nalaskowski, N. Sinha, J.N. Greeley, Z. Clark, H. Du, W.P. Johnson and J.D. Miller	

III. Drying

Drying of High Aspect Ratio Structures: A Comparison of Drying Techniques via Electrical Stiction Analysis	87
A. Pacco, M. Wada, T. Bearda and P.W. Mertens	
Relationship between Atmospheric Humidity and Watermark Formation in IPA Dry of Si Wafer after HF Clean	91
N. Kurumoto, A. Eitoku and K. Miya	

IV. Metrology

Complementary Metrology within a European Joint Laboratory	97
A. Nutsch, B. Beckhoff, R. Altmann, J.A. Van den Berg, D. Giubertoni, P. Hönicke, M. Bersani, A. Leibold, F. Meirer, M. Müller, G. Pepponi, M. Otto, P. Petrik, M. Reading, L. Pfitzner and H. Ryssel	
Highly Sensitive Detection of Inorganic Contamination	101
B. Beckhoff, A. Nutsch, R. Altmann, G. Borionetti, C. Pello, M.L. Polignano, D. Codegoni, S. Grasso, E. Cazzini, M. Bersani, P. Lazzeri, S. Gennaro, M. Kolbe, M. Müller, P. Kregsamer and F. Posch	
Trace Metallic Contamination Analysis on Wafer Edge and Bevel by TXRF and VPD-TXRF	105
H. Takahara and K. Tsugane	
Surface Potential Difference Imaging Applied to Wet Clean Monitoring	109
A. Danel, S. Sage, M.C. Roure, D. Peters, J. Hawthorne and R. Spicer	

V. Contamination Control

Metallic Contamination Control in Leading-Edge ULSI Manufacturing	115
A. Shimazaki, H. Sakurai, M. Iwase, R. Yoshimura and T. Tada	
Molybdenum Contamination in Silicon: Detection and Impact on Device Performances	123
D. Codegoni, M.L. Polignano, D. Caputo, A. Riva, E. Blot, D. Coulon, P. Maillot and N. Pic	
Developing a High Volume Manufacturing Wet Clean Process to Remove BF₂ Implant Induced Molybdenum Contamination	127
A. Sehgal, H.H. Huang, J. Ramdani, J. Klatt, C. Printy, S. Ruby and T. Thibeault	
Impact of Metal-Ion Contaminated Silica Particles on Gate Oxide Integrity	131
I. Rink, F. Wali and D.M. Knotter	
Monitoring System for Airborne Molecular Contamination (AMC) in Semiconductor Manufacturing Areas and Micro-Environments	135
M. Otto, A. Leibold, L. Wulf, M. Hurlebaus and L. Pfitzner	
Reduction of Airborne Molecular Contamination on 300 mm Front Opening Unified POD (FOUP) and Wafers Surface by Vacuum Technology	139
P. Maquin and H. Kambara	
Study of the Volatile Organic Contaminants Absorption and their Reversible Outgassing by FOUPs	143
H. Fontaine, S. Cetre, M. Veillerot and A. Danel	
Prevention of Condensation Defects on Contact Patterns by Improving Rinse Process	151
J.M. Oh, J.N. Han, K.T. Lee, C.K. Hong, W.S. Han, J.T. Moon and J.G. Park	
Single Wafer Ozone-Based Processing for Effective Edge Fluoropolymer Cleaning	155
J. Niccoli, M. Cogrono, M. Eastlack, D. McCane, C. Carlson, E. Young and D. Chapek	
Cleanliness Management in Advanced Microelectronic	159
Y. Borde, A. Danel, A. Roche, H. Fontaine and C. Brych	

VI. Front End of Line: Surface Preparation and Etching

Surface Preparation and Passivation of III-V Substrates for Future Ultra-High Speed, Low Power Logic Applications

W. Rachmady, J. Blackwell, G. Dewey, M. Hudait, M. Radosavljevic, R. Turkot Jr. and R. Chau 165

Preparation and Characterization of Self-Assembled Monolayers on Germanium Surfaces

M. Lommel, P. Hönicke, M. Kolbe, M. Müller, F. Reinhardt, P. Möbus, E. Mankel, B. Beckhoff and B.O. Kolbesen 169

Application of Single-Wafer Wet Cleaning Prior to Epitaxial SiGe Process

K. Sano, M. Wada, F.E. Leys, R. Loo, A. Hikavy, P.W. Mertens, J. Snow, A. Izumi, K. Miya and A. Eitoku 173

Low Temperature Pre-Epi Treatment: Critical Parameters to Control Interface Contamination

R. Loo, A. Hikavy, F.E. Leys, M. Wada, K. Sano, B. De Vos, A. Pacco, M. Bargallo Gonzalez, E. Simoen, P. Verheyen, W. Vanherle and M. Caymax 177

Silicon Surface Preparation and Passivation by Vapor Phase of Heavy Water

A.E. Pap, Z. Nényei, G. Battistig and I. Bársony 181

Defects of Silicon Substrates Caused by Electro-Static Discharge in Single Wafer Cleaning Process

Y. Hagimoto, H. Iwamoto, Y. Honbe, T. Fukunaga and H. Abe 185

Three-Step Room Temperature Wet Cleaning Process for Silicon Substrate

R. Hasebe, A. Teramoto, T. Suwa, R. Kuroda, S. Sugawa and T. Ohmi 189

Effect of Wet Treatment on Stability of Spin-On Dielectrics for STI Gap-Filling in Nanoscale Memory

G.H. Kim, S.Y. Park, S.S. Pyo, J.H. Han, J.N. Kim, K.J. Oh, C.K. Ryu, Y.S. Choi, N.J. Kwak and S.K. Park 193

Influence of Wet Cleaning on Tungsten Deposited with Different Techniques

A. Votta, F. Pipia, S. Borsari, E. Ravizza, A.C. Elbaz, M. Alessandri, E. Bellandi and C. Bresolin 197

VII. Front End of Line: Etching

Etch Rate Study of Germanium, GaAs and InGaAs: A Challenge in Semiconductor Processing

S. Sioncke, D.P. Brunco, M. Meuris, O. Uwamahoro, J. Van Steenberg, E. Vrancken and M.M. Heyns 203

Poly-Silicon Etch with Diluted Ammonia: Application to Replacement Gate Integration Scheme

F. Sebaai, J.I. Del Agua Borniquel, R. Vos, P. Absil, T. Chiarella, C. Vrancken, P. Boelen and E. Baiya 207

Advances on 45nm SiGe-Compatible NiPt Salicide Process

Y.W. Chen, N.T. Ho, J. Lai, T.C. Tsai, C.C. Huang, S.F. Tzou and J.M.M. Chu 211

Impact of Galvanic Corrosion on Metal Gate Stacks

M. Wada, S. Garaud, I. Ferain, N. Collaert, K. Sano, J. Snow, R. Vos, L.H.A. Leunissens, P.W. Mertens and A. Eitoku 215

Photoresist Adhesion during Wet Etch on Single Wafer Tool

P. Garnier, B. Pernet, Y. Gomez, C. Duluard, A. Torres, D. Barge, M. Gatefait and D. Lévy 219

Surface Texturization and Interface Passivation of Mono-Crystalline Silicon Substrates by Wet Chemical Treatments

W. Sievert, K.U. Zimmermann, B. Hartmann, C. Klimm, K. Jacob and H. Angermann 223

Mechanism of Plasma-Less Gaseous Etching Process for Damaged Oxides from the Ion Implantation Process

S. Saito, Y. Hagimoto, H. Iwamoto and Y. Muraki 227

Current Advances in Anhydrous HF/Organic Solvent Processing of Semiconductor Surfaces

P. Roman, K. Torek, K. Shanmugasundaram, P. Mumbauer, D. Vestyk, P. Hammond and J. Ruzyllo 231

Co-Solvent Effect on the HF/CO₂ Dry Etching of Sacrificial Oxides

J.H. Bae, J.M. Jung and K.T. Lim 235

A Novel Vapor Phase Etching Process for Si S. Verhaverbeke	239
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VIII. Front End of Line: Post Ion Implantation Photo Resist Strip

Material Loss Impact on Device Performance for 32nm CMOS and Beyond B.K. Kirkpatrick, J.J. Chambers, S.L. Prins, D.J. Riley, W.Z. Xiong and X. Wang	245
Evaluation of Plasma Strip Induced Substrate Damage K.P. Han, S. Luo, O. Escorcia, C. Waldfried and I.L. Berry	249
Post Extension Ion Implant Photo Resist Strip for 32 nm Technology and beyond G. Mannaert, L. Witters, D. Shamiryan, W. Boullart, K. Han, S. Luo, A. Falepin, R. Sonnemans, I.L. Berry and C. Waldfried	253
Influence of Dry Ashing and Wet Treatments on NVM Metal Gate Structures A.C. Elbaz, E. Bellandi, C. De Marco, L.M. Avaro, E. Ravizza, R. Piva and M. Alessandri	257
Chemical and Mechanical Analysis of HDIS Residues Using Auger Electron Spectroscopy and Nanoindentation A.V. Kadavanich, S.H. Shim, H.M. Meyer, S.E. Savas and E. Lara-Curzio	261
Shortening of Plasma Strip Process Resulting in Better Removal of Photo Resist after High Dose Implantation A. Zakharov, M. Lenski, S. Metzger and C. Krüger	265
Stripping and Cleaning of High-Dose Ion-Implanted Photoresists Using a Single-Wafer, Single-Chamber Dry/Wet Hybrid System Y.J. Kim, J.H. Lee, K.J. Seo, C.R. Yoon, E.S. Roh, J.K. Cho and T. Hattori	269
Post Ion-Implant Photoresist Stripping Using Steam and Water: Pre-Treatment in a Steam Atmosphere and Steam-Water Mixed Spray T. Sanada, M. Watanabe, A. Hayashida and Y. Isago	273
Steam-Injected SPM Process for All-Wet Stripping of Implanted Photoresist D. DeKraker, B. Pasker, J.W. Butterbaugh, K.K. Christenson and T.J. Wagener	277
Novel Methods for Wet Stripping High Dose Implanted Photoresist Using Sulfur Trioxide E.J. Bergman and J.D. Leonhard	281
All Wet Photoresist Strip by Solvent Aerosol Spray M. Wada, K. Sano, J. Snow, R. Vos, L.H.A. Leunissens, P.W. Mertens and A. Eitoku	285
Stripping of Ion Implanted Photoresist by CO₂ Cryogenic Pre-Treatment Followed by Wet Cleaning S. Malhouitre, R. Vos, S. Banerjee, P. Cheng, T. Bearda and P.W. Mertens	289

IX. Back End of Line: Post Dielectric Etch Photo Resist Strip

Porous Low-k Wet Etch in HF-Based Solutions: Focus on Cleaning Process Window, "Pore-Sealing" and "k Recovery" L. Broussous, W. Puyrenier, D. Rebiscoul, V. Rouessac and A. Ayrat	295
Photoresist Removal Using Alternative Chemistries and Pressures I.G. Song, C. Timmons, G. Levitin and D.W. Hess	303
Ozone Chemistry for BEOL Resist Stripping – A Systematic Analytical Attempt to Understand the Interaction of O₃ with Modern DUV-Resists M. Guder, M. Pellowaska, M. Pohland, M. Dalmer and B.O. Kolbesen	311
Design and Development of Novel Remover for Cu/Porous Low-k Interconnects T. Suzuki, A. Otake and T. Aoki	315
Surface Energy and Wetting Behaviour of Plasma Etched Porous SiCOH Surfaces and Plasma Etch Residue Cleaning Solutions N. Ahner, M. Schaller, C. Bartsch, E. Baryschpolec and S.E. Schulz	319
Modification of Photoresist by UV for Post-Etch Wet Strip Applications Q.T. Le, E. Kesters, L. Prager, M. Claes, M. Lux and G. Vereecke	323
Recyclable Fluorine-Based Cleaning Solvents for Resist Removal H. Okamoto and H. Namatsu	327
Cu Dendrite Formation in Post Trench Etch Cleaning J.S. Heo, J.H. Oh, H.J. Shin and N.I. Lee	331

The Interaction of Sublimed Iminodiacetic Acid with a Cu{110} Surface D.W. Tee, S.M. Francis, N.V. Richardson, C. Reid and L. McGhee	335
Advances in Test Wafer Reclaim Technology – Wet Stripping Porous Low-k Films with No Substrate Damage M. Robson, K.A. Fletcher, P. Jiang, M.B. Korzenski, A. Upham, T. Haigh Jr. and T.J.C. Hsieh	339
Electrochemical Behavior of Cobalt in Post-Via Etch Cleaning Solutions S. Bilouk, C. Pernel, L. Broussous, V. Ivanova and R. Nogueira	343

X. Back End of Line: Post Metal Etch Photo Resist Strip

Characterization of Post Etch Residues Depending on Resist Removal Processes after Aluminum Etch M. Heidenblut, D. Sturm, A. Lechner and F. Faupel	349
Impact of Dry Etch and Ash Conditions on Removability of Plasma Etch Residues in Al-Metallization. Approach to Improve PER Cleaning Efficiency by EHS-Friendly Aqueous Remover B. Ferstl, A. Klipp, M. Essig and M. Heidenblut	353
Borderless via Clean Study for Minimizing Al-Cu Loss in 58nm Flash Devices C.K. Chen, P.C. Yu, M.H. Lee, C.N. Wu and H. Matsuo	357

XI. Back End of Line: Post Cu CMP Cleaning

Effect of Various Cleaning Solutions and Brush Scrubber Kinematics on the Frictional Attributes of Post Copper CMP Cleaning Process Y. Sampurno, Y. Zhuang, X. Gu, S. Theng, T. Nemoto, T. Sun, F. Sudargho, A. Teramoto, A. Philipossian and T. Ohmi	363
The Effect of PVA Brush Scrubbing on Post CMP Cleaning Process for Damascene Cu Interconnection H.C. Cho, Y.M. Kim, H.S. Lee, S.B. Joo and H.D. Jeong	367
Cu Surface Characterization after Wet Cleaning Processes F. Pipia, A. Votta, A.C. Elbaz, S. Grasso, E. Ravizza, S. Spadoni and M. Alessandri	371
Impact of CMP Polish and pCMP Cleaning on Adhesion of SiCN Capping Layer on PECVD-Derived Porous OSG and Copper D.M. Gage, A.D.W. Thiel, R.H. Dauskardt, M.K. Haas, L.M. Matz, M.L. O'Neill, T.M. Wieder, G. Banerjee and M.B. Rao	377
Damage-Free Post-CMP Cleaning Solution for Low-k Fluorocarbon on Advanced Interconnects X. Gu, T. Nemoto, A. Teramoto, R. Hasebe, T. Ito and T. Ohmi	381
Process Dependence on Defectivity Count on Copper and Dielectric Surfaces in Post-Copper CMP Cleaning J. Daviot and J. Vaes	385
A Novel Copper Interconnection Cleaning by Atomic Hydrogen Using Diluted Hydrogen Gas K. Abe and A. Izumi	389